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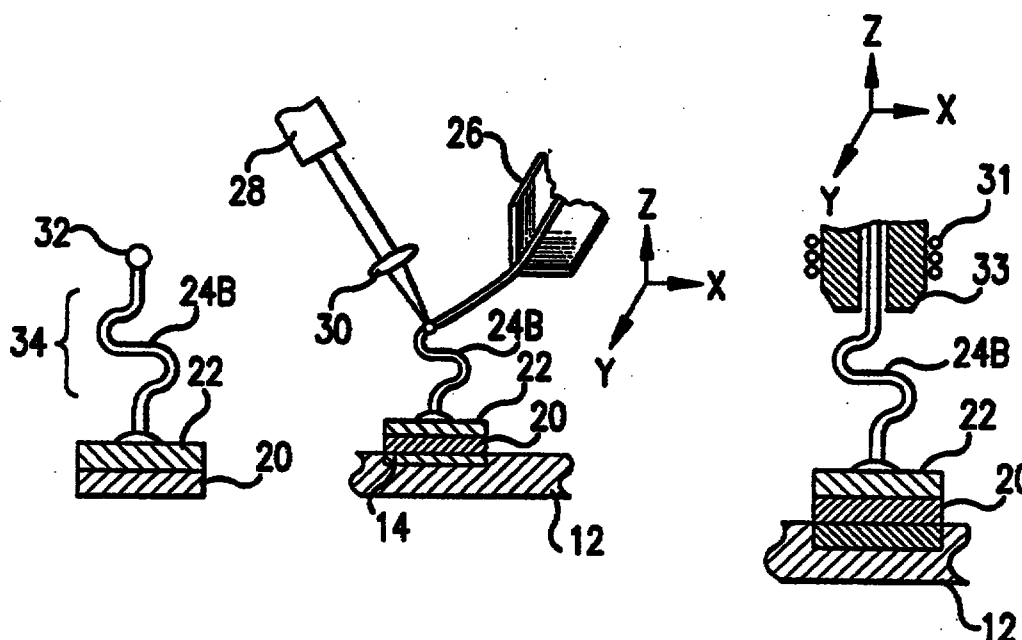
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(54) Title: METHOD FOR FORMING CONTACT PINS FOR SEMICONDUCTOR DICE AND INTERCONNECTS



(57) Abstract

A method for forming contact pins adapted to form an electrical connection with a mating contact location is provided. In a first embodiment, the contact pins are formed on an interconnect used for testing a semiconductor die and are adapted to establish an electrical connection with the bond pads of the die. In a second embodiment, the contact pins are formed directly on the bond pads of a die and can be used for establishing a permanent or temporary electrical connection to the pads. The contact pins include a base portion attached to the die or interconnect, a compliant spring segment, and a contact ball at the tip. The contact pins are formed using a wire bonding process or a welding process in which a metal wire is simultaneously heated and shaped into a compliant structure as it is attached to the die or interconnect.